

U.S. Department of Commerce, Patent and Trademark Office		Docket No.	Serial No.
		APPM/1931	08/856,116
LIST OF RELEVANT ART CITED BY APPLICANT <i>NOV 16 1998</i>		Applicant	
(Use several sheets if necessary)		Fusen Chen et al.	
		Filing Date	Group
		May 14, 1997	1104

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
BES	AA	5,308,793	05/03/1994	TAGUCHI ET AL.			
BES	AB	5,371,042	12/06/1994	ONG			RECEIVED
BES	AC	5,486,492	01/23/1996	YAMAMOTO ET AL.			APR 1 1999
	AD						GROUP 1700
	AE						
	AF						
	AG						
	AH						
	AI						RECEIVED NOV 25 1998
	AJ						RECEIVED GROUP 2100 - 07 1999
	AK						TECHNOLOGY CENTER 2000

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
BES	AL	08213119	07-24-1996	JAPAN (Abstract)			X	
	AM							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AQ	PCT Notification of Transmittal of The International Search Report or the Declaration and PCT International Search Report
	AR	Donald S. Gardner, Jin Onuki, Kazue Kudoo, Yutaka Misawa, Quat T. Vu, "Encapsulated copper interconnection devices using sidewall barriers, 1995, pages 104-119
	AT	Si-Yeoul Jang, Sung-Man Lee "Tantalum and niobium as a diffusion barrier between copper and silicon," 1996, pages 271-278
	AS	Tadashi Iijima, Yoshiakai Shimooka, and Kyoichi Suguro, "An Amorphous Ti-Si-N Diffusion Barrier Layer for Cu Interconnections," Vol. 78, No. 12, 1995, pages 67-74

Examiner Bernard E. Soule Date Considered 7/2/99

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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Applicant

Liang-Yuh Chen, Fusen Chen, Moshe Eizenberg, and Roderick Craig Mosely

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		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
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## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

BES	AN	K. Mikagi, H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa, "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film," 1996 IEEE, pp. 365-368
BES	AO	Y. Shacham-Diamand, V. Dubin and M. Angyal, "Electroless Copper Deposition for ULSI," 1995 Elsevier Science S.A., pp. 93-103
BES	AP	Electromigration and Diffusion in Pure Cu and Cu(Sn) Alloys, C.-K. Hu, K. L. Lee, D. Gupta, and P. Blauner, Mat. Res. Soc. Symp. Vol 427, (96-105)

Examiner

Bernard E. Souw

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07/02/99

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	AM							
	AN							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

BES	AO	Electromigration Failure Distributions for Multi-Large Interconnects as a Function of Line Width: Experiments and Simulation, D.D. Brown, J.E. Sanchez, Jr., V. Pham, P.R. Besser, M.A. Korhonen, and C.-Y. Li, Mat. Res. Soc. Symp. Vol 427
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	AQ	

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